ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Par	PC. Bannockl	ourn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su compasses	bstances v s all lower	within the manufactu level materials for w	rer listed which the 1	item. Note: nanufactur	if the item is an as er has engineering	sembly with low responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg					Ifg Informa	ation			
upplier Information														
Company name* Compa			mpany unique ID			Unique ID Authority				Respon	Response Date*			
onsemi									2025-06-08					
Contact Name	act Name Title - Contact					Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Envir			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repr			resentative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	М	Ianufacturing Site		Weight*	UOM	Unit Type	
	MUN52	IUN5232T1G SS SC70 BR XSTR		TR NPN 50V		2025-06-08		C	CN1		6.0	mg	Each	
Ianufacturing Proccess Informa	tion		·				·	i						
Terminal Plating / Grid Array Ma	aterial 7	al Terminal Base Alloy J-S		J-STD-020 MSI	L Rating	Peak Process Body Temperat		emperature	ure Max Time at Peak Temper		ture Nun	nber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	seco	nds 3			
omments														
vel 1 - maximum time at peak temperatu	ire during so	ldering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.1	mg	Supplier	Silicon (Si)	7440-21-3		0.1	mg	
Lead Frame	2.08	mg	В	Nickel (Ni)	7440-02-0		0.7966	mg	
			Supplier	Iron (Fe)	7439-89-6		1.1003	mg	
			Supplier	Copper (Cu)	7440-50-8		0.183	mg	
Mold Compound-Black	3.7	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.37	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0185	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.5365	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		2.405	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.37	mg	
Plating	0.11	mg	Supplier	Tin (Sn)	7440-31-5		0.11	mg	
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg	